



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2025-06-24
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDRF CHAMPION	Representative title	MDRF Material Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32H755IIK3	59MR*450XXXV	A	9996	2025-06-24
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	106	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Tin - 3.5Ag	Not Applicable	NAC	0	
Package designator	Package size	Number of instances	Shape	
BGA	10x10	201	Bulk solder	
Comment	Package : A0E7 UFBGA 10X10X0.6 176+25 P0.65 8249558			

QueryList : RoHS Directive 2011/65/EU - 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	
,		

QueryList : REACH-21st January 2025				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	#N/A			



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	59MR*450XXXV		106.185		600000	100000				
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or dies	M-011 Other inorganic materials	4.114	mg	supplier	die	Silicon (Si)	7440-21-3		3.934	mg	956302	37051				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.021	mg	5183	201				
				supplier	metallization	Copper (Cu)	7440-50-8		0.067	mg	16254	630				
				supplier	metallization	Nickel (Ni)	7440-02-0		0.000	mg	59	2				
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.011	mg	2650	103				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	471	18				
				supplier	metallization	Tungsten (W)	7440-33-7		0.000	mg	59	2				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.078	mg	19022	737				
				Substrate (101424157)	Other organic materials	33.581	mg	supplier	CORE	Fibrous-Glass-Wool	65997-17-3		4.727	mg	140758	44515
supplier	CORE	Formaldehyde Polymer with (Chloromethyl)Oxirane	28906-96-9						1.203	mg	35827	11330				
supplier	CORE	Triazine	25722-66-1						1.203	mg	35827	11330				
supplier	CORE	Silicon dioxide	7631-86-9						2.941	mg	87578	27697				
supplier	COPPER FOIL	Copper (Cu)	7440-50-8						10.074	mg	299991	94872				
supplier	SOLDERMASK (AUS308)	Cured Resin	Proprietary						4.551	mg	135523	42859				
supplier	SOLDERMASK (AUS308)	Phthalocyanine Blue	147-14-8						0.015	mg	440	139				
supplier	SOLDERMASK (AUS308)	Organic Pigment	Proprietary						0.007	mg	220	70				
supplier	SOLDERMASK (AUS308)	Silica	7631-86-9						0.066	mg	1980	626				
supplier	SOLDERMASK (AUS308)	Barium sulfate	7727-43-7						2.298	mg	68422	21638				
supplier	SOLDERMASK (AUS308)	Talc	14807-96-6						0.266	mg	7920	2505				
supplier	SOLDERMASK (AUS308)	Organic Filler	Proprietary						0.089	mg	2640	835				
supplier	SOLDERMASK (AUS308)	Antifoamer and Leveling Agent	Proprietary						0.096	mg	2860	904				
supplier	NI PLATING	Nickel (Ni)	7440-02-0						5.495	mg	163634	51749				
supplier	AU PLATING	Gold (Au)	7440-57-5						0.550	mg	16378	5180				
DAF (EM-760L2-P)	Other organic materials	0.674	mg					supplier	GLUE	Synthetic Rubber	Proprietary		0.270	mg	400000	2539
								supplier	GLUE	Amorphous Silica	7631-86-9		0.337	mg	500000	3174
				supplier	GLUE	Phenol Resin	Proprietary		0.067	mg	100000	635				
Bonding Wires (Cu)	Other inorganic materials	1.106	mg	supplier	BONDING WIRE	Copper	7440-50-8		1.073	mg	970500	10109				
				supplier	BONDING WIRE	Palladium	7440-05-3		0.031	mg	28000	292				
				supplier	BONDING WIRE	Gold	7440-57-5		0.002	mg	1500	16				
Solder balls (Sn3.5Ag)	Other inorganic materials	6.241	mg	supplier	SOLDERBALL	Tin (Sn)	7440-31-5		6.023	mg	965000	56718				
				supplier	SOLDERBALL	Silver (Ag)	7440-22-4		0.218	mg	35000	2057				
Encapsulation (G770FE)	Other organic materials	60.469	mg	supplier	MOLDING COMPOUND	Epoxy Resin A	Proprietary		1.814	mg	30000	17084				
				supplier	MOLDING COMPOUND	Epoxy Resin B	1675-54-3		1.814	mg	30000	17084				
				supplier	MOLDING COMPOUND	Phenol Resin	Proprietary		2.782	mg	46000	26196				
				supplier	MOLDING COMPOUND	Silica(Amorphous) A	60676-86-0		43.780	mg	724000	412295				
				supplier	MOLDING COMPOUND	Silica(Amorphous) B	7631-86-9		9.070	mg	150000	85420				
				supplier	MOLDING COMPOUND	Aluminum Hydroxide	21645-51-2		0.907	mg	15000	8542				
				supplier	MOLDING COMPOUND	Carbon Black	1333-86-4		0.302	mg	5000	2847				